

ABSTRACT OF THE DISCLOSURE

5 An integrated circuit package which may include
the dispense of a second encapsulant material (or
fillet) different from the first underfill material on
an integrated circuit package which may include an
integrated circuit that is mounted to a substrate. The
package may further have a first underfill material and
a second underfill material that are attached to the
10 integrated circuit and the substrate. The second
encapsulant material may be tailored to inhibit
cracking of the epoxy itself that propagates into the
substrate during thermo-mechanical loading.